



Welcome to [E-XFL.COM](https://www.e-xfl.com)

What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

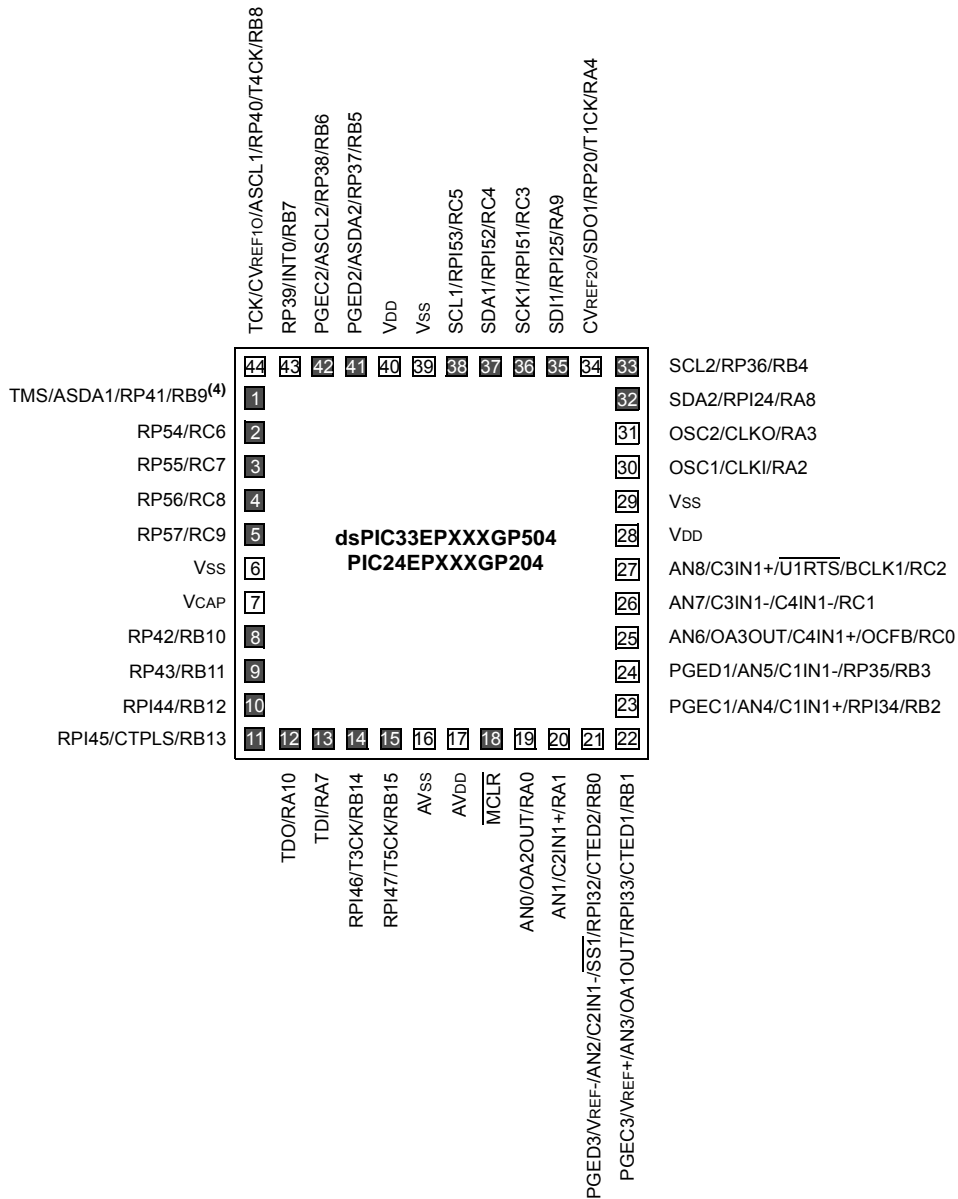
Details

Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	70 MIPS
Connectivity	I ² C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	21
Program Memory Size	256KB (85.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep256mc202-i-sp

Pin Diagrams (Continued)

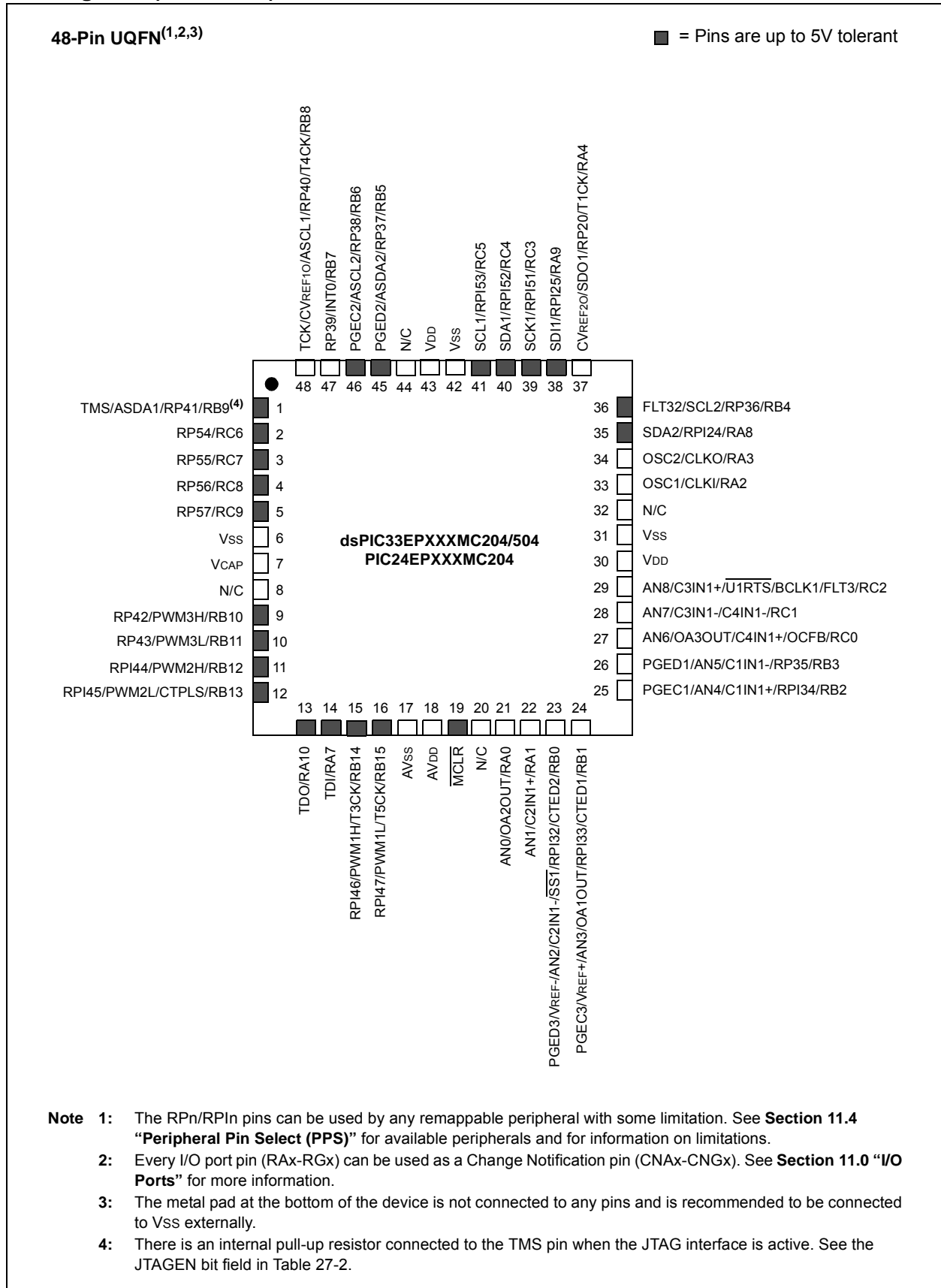
44-Pin VTLA^(1,2,3)

■ = Pins are up to 5V tolerant



- Note 1:** The RPN/RPIN pins can be used by any remappable peripheral with some limitation. See **Section 11.4 “Peripheral Pin Select (PPS)”** for available peripherals and for information on limitations.
- Note 2:** Every I/O port pin (RAX-RGX) can be used as a Change Notification pin (CNAX-CNGX). See **Section 11.0 “I/O Ports”** for more information.
- Note 3:** The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.
- Note 4:** There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

Pin Diagrams (Continued)



- Note 1:** The RPN/RPI pins can be used by any remappable peripheral with some limitation. See **Section 11.4 “Peripheral Pin Select (PPS)”** for available peripherals and for information on limitations.
- Note 2:** Every I/O port pin (RAX-RGX) can be used as a Change Notification pin (CNAX-CNGX). See **Section 11.0 “I/O Ports”** for more information.
- Note 3:** The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to Vss externally.
- Note 4:** There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

TABLE 4-1: CPU CORE REGISTER MAP FOR dsPIC33EPXXXMC20X/50X AND dsPIC33EPXXXGP50X DEVICES ONLY (CONTINUED)

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets	
SR	0042	OA	OB	SA	SB	OAB	SAB	DA	DC	IPL2	IPL1	IPL0	RA	N	OV	Z	C	0000	
CORCON	0044	VAR	—	US<1:0>		EDT	DL<2:0>			SATA	SATB	SATDW	ACCSAT	IPL3	SFA	RND	IF	0020	
MODCON	0046	XMODEN	YMODEN	—	—	BWM<3:0>				YWM<3:0>			XWM<3:0>				0000		
XMODSRT	0048	XMODSRT<15:0>																—	0000
XMODEND	004A	XMODEND<15:0>																—	0001
YMODSRT	004C	YMODSRT<15:0>																—	0000
YMODEND	004E	YMODEND<15:0>																—	0001
XBREV	0050	BREN	XBREV<14:0>															0000	
DISICNT	0052	—	—	DISICNT<13:0>														0000	
TBLPAG	0054	—	—	—	—	—	—	—	—	TBLPAG<7:0>									0000
MSTRPR	0058	MSTRPR<15:0>																0000	

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

FIGURE 4-21: BIT-REVERSED ADDRESSING EXAMPLE

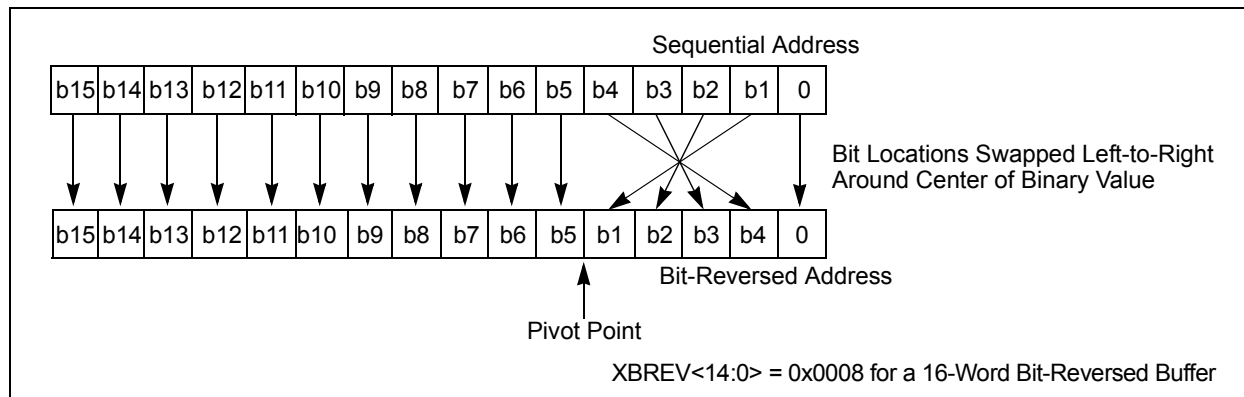


TABLE 4-64: BIT-REVERSED ADDRESSING SEQUENCE (16-ENTRY)

Normal Address					Bit-Reversed Address				
A3	A2	A1	A0	Decimal	A3	A2	A1	A0	Decimal
0	0	0	0	0	0	0	0	0	0
0	0	0	1	1	1	0	0	0	8
0	0	1	0	2	0	1	0	0	4
0	0	1	1	3	1	1	0	0	12
0	1	0	0	4	0	0	1	0	2
0	1	0	1	5	1	0	1	0	10
0	1	1	0	6	0	1	1	0	6
0	1	1	1	7	1	1	1	0	14
1	0	0	0	8	0	0	0	1	1
1	0	0	1	9	1	0	0	1	9
1	0	1	0	10	0	1	0	1	5
1	0	1	1	11	1	1	0	1	13
1	1	0	0	12	0	0	1	1	3
1	1	0	1	13	1	0	1	1	11
1	1	1	0	14	0	1	1	1	7
1	1	1	1	15	1	1	1	1	15

5.2 RTSP Operation

RTSP allows the user application to erase a single page of memory and to program two instruction words at a time. See the General Purpose and Motor Control Family tables (Table 1 and Table 2, respectively) for the page sizes of each device.

For more information on erasing and programming Flash memory, refer to “**Flash Programming**” (DS70609) in the “*dsPIC33/PIC24 Family Reference Manual*”.

5.3 Programming Operations

A complete programming sequence is necessary for programming or erasing the internal Flash in RTSP mode. The processor stalls (waits) until the programming operation is finished.

For erase and program times, refer to Parameters D137a and D137b (Page Erase Time), and D138a and D138b (Word Write Cycle Time) in Table 30-14 in **Section 30.0 “Electrical Characteristics”**.

Setting the WR bit (NVMCON<15>) starts the operation and the WR bit is automatically cleared when the operation is finished.

5.3.1 PROGRAMMING ALGORITHM FOR FLASH PROGRAM MEMORY

Programmers can program two adjacent words (24 bits x 2) of program Flash memory at a time on every other word address boundary (0x000002, 0x000006, 0x00000A, etc.). To do this, it is necessary to erase the page that contains the desired address of the location the user wants to change.

For protection against accidental operations, the write initiate sequence for NVMKEY must be used to allow any erase or program operation to proceed. After the programming command has been executed, the user application must wait for the programming time until programming is complete. The two instructions following the start of the programming sequence should be NOPs.

Refer to **Flash Programming**” (DS70609) in the “*dsPIC33/PIC24 Family Reference Manual*” for details and codes examples on programming using RTSP.

5.4 Flash Memory Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note: In the event you are not able to access the product page using the link above, enter this URL in your browser:
<http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464>

5.4.1 KEY RESOURCES

- “**Flash Programming**” (DS70609) in the “*dsPIC33/PIC24 Family Reference Manual*”
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related “*dsPIC33/PIC24 Family Reference Manual*” Sections
- Development Tools

5.5 Control Registers

Four SFRs are used to erase and write the program Flash memory: NVMCON, NVMKEY, NVMADRH and NVMADRL.

The NVMCON register (Register 5-1) enables and initiates Flash memory erase and write operations.

NVMKEY (Register 5-4) is a write-only register that is used for write protection. To start a programming or erase sequence, the user application must consecutively write 0x55 and 0xAA to the NVMKEY register.

There are two NVM Address registers: NVMADRH and NVMADRL. These two registers, when concatenated, form the 24-bit Effective Address (EA) of the selected word for programming operations or the selected page for erase operations.

The NVMADRH register is used to hold the upper 8 bits of the EA, while the NVMADRL register is used to hold the lower 16 bits of the EA.

REGISTER 8-7: DMAxPAD: DMA CHANNEL x PERIPHERAL ADDRESS REGISTER⁽¹⁾

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	
PAD<15:8>								
bit 15								bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	
PAD<7:0>								
bit 7								bit 0

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
 -n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 15-0 **PAD<15:0>**: Peripheral Address Register bits

Note 1: If the channel is enabled (i.e., active), writes to this register may result in unpredictable behavior of the DMA channel and should be avoided.

REGISTER 8-8: DMAxCNT: DMA CHANNEL x TRANSFER COUNT REGISTER⁽¹⁾

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	
—	—	CNT<13:8> ⁽²⁾						
bit 15								bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	
CNT<7:0> ⁽²⁾								
bit 7								bit 0

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
 -n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13-0 **CNT<13:0>**: DMA Transfer Count Register bits⁽²⁾

Note 1: If the channel is enabled (i.e., active), writes to this register may result in unpredictable behavior of the DMA channel and should be avoided.

2: The number of DMA transfers = CNT<13:0> + 1.

REGISTER 11-24: RPOR6: PERIPHERAL PIN SELECT OUTPUT REGISTER 6

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP57R<5:0>					
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP56R<5:0>					
bit 7							bit 0

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
 -n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

- bit 15-14 **Unimplemented:** Read as '0'
- bit 13-8 **RP57R<5:0>:** Peripheral Output Function is Assigned to RP57 Output Pin bits
 (see Table 11-3 for peripheral function numbers)
- bit 7-6 **Unimplemented:** Read as '0'
- bit 5-0 **RP56R<5:0>:** Peripheral Output Function is Assigned to RP56 Output Pin bits
 (see Table 11-3 for peripheral function numbers)

REGISTER 11-25: RPOR7: PERIPHERAL PIN SELECT OUTPUT REGISTER 7

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP97R<5:0>					
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
 -n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

- bit 15-14 **Unimplemented:** Read as '0'
- bit 13-8 **RP97R<5:0>:** Peripheral Output Function is Assigned to RP97 Output Pin bits
 (see Table 11-3 for peripheral function numbers)
- bit 7-0 **Unimplemented:** Read as '0'

REGISTER 16-8: PDCx: PWMx GENERATOR DUTY CYCLE REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PDCx<15:8>							
bit 15				bit 8			

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PDCx<7:0>							
bit 7				bit 0			

Legend:
 R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
 -n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 15-0 **PDCx<15:0>**: PWMx Generator # Duty Cycle Value bits

REGISTER 16-9: PHASEx: PWMx PRIMARY PHASE-SHIFT REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PHASEx<15:8>							
bit 15				bit 8			

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PHASEx<7:0>							
bit 7				bit 0			

Legend:
 R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
 -n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 15-0 **PHASEx<15:0>**: PWMx Phase-Shift Value or Independent Time Base Period for the PWM Generator bits

Note 1: If ITB (PWMCONx<9>) = 0, the following applies based on the mode of operation:
 Complementary, Redundant and Push-Pull Output mode (PMOD<1:0> (IOCON<11:10>) = 00, 01 or 10),
 PHASEx<15:0> = Phase-shift value for PWMxH and PWMxL outputs

2: If ITB (PWMCONx<9>) = 1, the following applies based on the mode of operation:
 Complementary, Redundant and Push-Pull Output mode (PMOD<1:0> (IOCONx<11:10>) = 00, 01 or 10),
 PHASEx<15:0> = Independent time base period value for PWMxH and PWMxL

REGISTER 16-12: TRGCONx: PWMx TRIGGER CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0
TRGDIV<3:0>				—	—	—	—
bit 15				bit 8			

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	TRGSTRT<5:0> ⁽¹⁾					
bit 7		bit 0					

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-12 **TRGDIV<3:0>**: Trigger # Output Divider bits
 1111 = Trigger output for every 16th trigger event
 1110 = Trigger output for every 15th trigger event
 1101 = Trigger output for every 14th trigger event
 1100 = Trigger output for every 13th trigger event
 1011 = Trigger output for every 12th trigger event
 1010 = Trigger output for every 11th trigger event
 1001 = Trigger output for every 10th trigger event
 1000 = Trigger output for every 9th trigger event
 0111 = Trigger output for every 8th trigger event
 0110 = Trigger output for every 7th trigger event
 0101 = Trigger output for every 6th trigger event
 0100 = Trigger output for every 5th trigger event
 0011 = Trigger output for every 4th trigger event
 0010 = Trigger output for every 3rd trigger event
 0001 = Trigger output for every 2nd trigger event
 0000 = Trigger output for every trigger event

bit 11-6 **Unimplemented**: Read as '0'

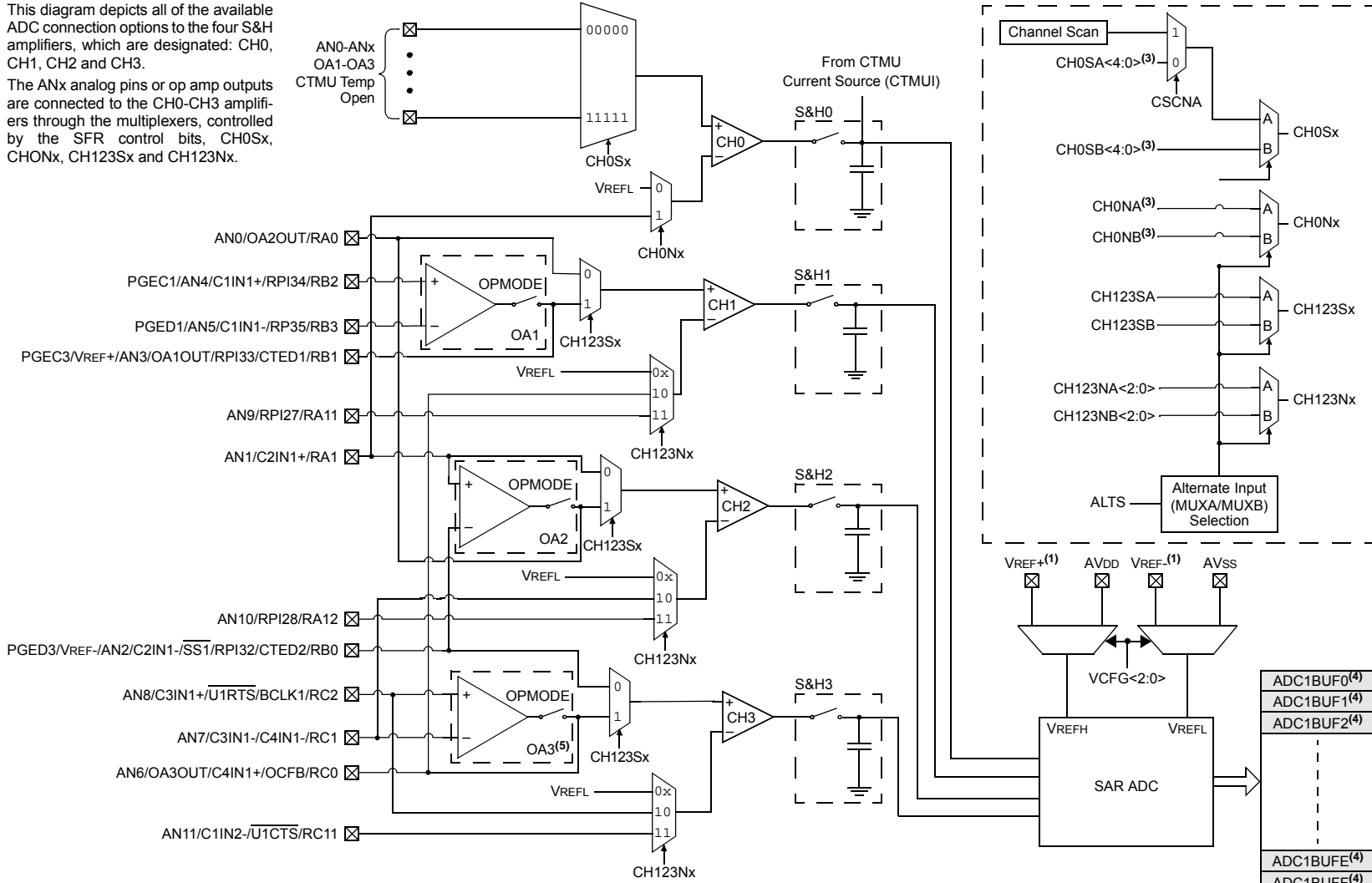
bit 5-0 **TRGSTRT<5:0>**: Trigger Postscaler Start Enable Select bits⁽¹⁾
 111111 = Waits 63 PWM cycles before generating the first trigger event after the module is enabled
 •
 •
 •
 000010 = Waits 2 PWM cycles before generating the first trigger event after the module is enabled
 000001 = Waits 1 PWM cycle before generating the first trigger event after the module is enabled
 000000 = Waits 0 PWM cycles before generating the first trigger event after the module is enabled

Note 1: The secondary PWM generator cannot generate PWMx trigger interrupts.

FIGURE 23-1: ADC MODULE BLOCK DIAGRAM WITH CONNECTION OPTIONS FOR ANx PINS AND OP AMPS

This diagram depicts all of the available ADC connection options to the four S&H amplifiers, which are designated: CH0, CH1, CH2 and CH3.

The ANx analog pins or op amp outputs are connected to the CH0-CH3 amplifiers through the multiplexers, controlled by the SFR control bits, CH0Sx, CH1Sx, CH2Sx and CH3Sx.



- Note**
- 1: VREF+, VREF- inputs can be multiplexed with other analog inputs.
 - 2: Channels 1, 2 and 3 are not applicable for the 12-bit mode of operation.
 - 3: These bits can be updated with Step commands from the PTG module. See Section 24.0 "Peripheral Trigger Generator (PTG) Module" for more information.
 - 4: When ADDMAEN (AD1CON4<8>) = 1, enabling DMA, only ADC1BUF0 is used.
 - 5: OA3 is not available for 28-pin devices.

REGISTER 23-3: AD1CON3: ADC1 CONTROL REGISTER 3

R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADRC	—	—	SAMC4 ⁽¹⁾	SAMC3 ⁽¹⁾	SAMC2 ⁽¹⁾	SAMC1 ⁽¹⁾	SAMC0 ⁽¹⁾
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADCS7 ⁽²⁾	ADCS6 ⁽²⁾	ADCS5 ⁽²⁾	ADCS4 ⁽²⁾	ADCS3 ⁽²⁾	ADCS2 ⁽²⁾	ADCS1 ⁽²⁾	ADCS0 ⁽²⁾
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ADRC:** ADC1 Conversion Clock Source bit
 1 = ADC internal RC clock
 0 = Clock derived from system clock

bit 14-13 **Unimplemented:** Read as '0'

bit 12-8 **SAMC<4:0>:** Auto-Sample Time bits⁽¹⁾
 11111 = 31 TAD
 •
 •
 •
 00001 = 1 TAD
 00000 = 0 TAD

bit 7-0 **ADCS<7:0>:** ADC1 Conversion Clock Select bits⁽²⁾
 11111111 = $TP \cdot (ADCS<7:0> + 1) = TP \cdot 256 = TAD$
 •
 •
 •
 00000010 = $TP \cdot (ADCS<7:0> + 1) = TP \cdot 3 = TAD$
 00000001 = $TP \cdot (ADCS<7:0> + 1) = TP \cdot 2 = TAD$
 00000000 = $TP \cdot (ADCS<7:0> + 1) = TP \cdot 1 = TAD$

- Note 1:** This bit is only used if SSRC<2:0> (AD1CON1<7:5>) = 111 and SSRCG (AD1CON1<4>) = 0.
2: This bit is not used if ADRC (AD1CON3<15>) = 1.

REGISTER 23-8: AD1CSSL: ADC1 INPUT SCAN SELECT REGISTER LOW^(1,2)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CSS15	CSS14	CSS13	CSS12	CSS11	CSS10	CSS9	CSS8
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CSS7	CSS6	CSS5	CSS4	CSS3	CSS2	CSS1	CSS0
bit 7							bit 0

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared
		x = Bit is unknown

bit 15-0 **CSS<15:0>**: ADC1 Input Scan Selection bits

1 = Selects ANx for input scan

0 = Skips ANx for input scan

Note 1: On devices with less than 16 analog inputs, all AD1CSSL bits can be selected by the user. However, inputs selected for scan, without a corresponding input on the device, convert VREFL.

2: CSSx = ANx, where x = 0-15.

25.3 Op Amp/Comparator Registers

REGISTER 25-1: CMSTAT: OP AMP/COMPARATOR STATUS REGISTER

R/W-0	U-0	U-0	U-0	R-0	R-0	R-0	R-0
PSIDL	—	—	—	C4EVT ⁽¹⁾	C3EVT ⁽¹⁾	C2EVT ⁽¹⁾	C1EVT ⁽¹⁾
bit 15							bit 8

U-0	U-0	U-0	U-0	R-0	R-0	R-0	R-0
—	—	—	—	C4OUT ⁽²⁾	C3OUT ⁽²⁾	C2OUT ⁽²⁾	C1OUT ⁽²⁾
bit 7							bit 0

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
 -n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

- bit 15 **PSIDL:** Comparator Stop in Idle Mode bit
 1 = Discontinues operation of all comparators when device enters Idle mode
 0 = Continues operation of all comparators in Idle mode
- bit 14-12 **Unimplemented:** Read as '0'
- bit 11 **C4EVT:** Op Amp/Comparator 4 Event Status bit⁽¹⁾
 1 = Op amp/comparator event occurred
 0 = Op amp/comparator event did not occur
- bit 10 **C3EVT:** Comparator 3 Event Status bit⁽¹⁾
 1 = Comparator event occurred
 0 = Comparator event did not occur
- bit 9 **C2EVT:** Comparator 2 Event Status bit⁽¹⁾
 1 = Comparator event occurred
 0 = Comparator event did not occur
- bit 8 **C1EVT:** Comparator 1 Event Status bit⁽¹⁾
 1 = Comparator event occurred
 0 = Comparator event did not occur
- bit 7-4 **Unimplemented:** Read as '0'
- bit 3 **C4OUT:** Comparator 4 Output Status bit⁽²⁾
 When CPOL = 0:
 1 = VIN+ > VIN-
 0 = VIN+ < VIN-
 When CPOL = 1:
 1 = VIN+ < VIN-
 0 = VIN+ > VIN-
- bit 2 **C3OUT:** Comparator 3 Output Status bit⁽²⁾
 When CPOL = 0:
 1 = VIN+ > VIN-
 0 = VIN+ < VIN-
 When CPOL = 1:
 1 = VIN+ < VIN-
 0 = VIN+ > VIN-

- Note 1:** Reflects the value of the of the CEVT bit in the respective Op Amp/Comparator Control register, CMxCON<9>.
- 2:** Reflects the value of the COUT bit in the respective Op Amp/Comparator Control register, CMxCON<8>.

**REGISTER 25-4: CMxMSKSRG: COMPARATOR x MASK SOURCE SELECT
CONTROL REGISTER (CONTINUED)**

bit 3-0 **SELSRCA<3:0>**: Mask A Input Select bits

1111 = FLT4
1110 = FLT2
1101 = PTGO19
1100 = PTGO18
1011 = Reserved
1010 = Reserved
1001 = Reserved
1000 = Reserved
0111 = Reserved
0110 = Reserved
0101 = PWM3H
0100 = PWM3L
0011 = PWM2H
0010 = PWM2L
0001 = PWM1H
0000 = PWM1L

REGISTER 25-6: CM_xFLTR: COMPARATOR x FILTER CONTROL REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	CFSEL2	CFSEL1	CFSEL0	CFLTREN	CFDIV2	CFDIV1	CFDIV0
bit 7							bit 0

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared
		x = Bit is unknown

- bit 15-7 **Unimplemented:** Read as '0'
- bit 6-4 **CFSEL<2:0>:** Comparator Filter Input Clock Select bits
 - 111 = T5CLK⁽¹⁾
 - 110 = T4CLK⁽²⁾
 - 101 = T3CLK⁽¹⁾
 - 100 = T2CLK⁽²⁾
 - 011 = Reserved
 - 010 = SYNCO1⁽³⁾
 - 001 = Fosc⁽⁴⁾
 - 000 = Fp⁽⁴⁾
- bit 3 **CFLTREN:** Comparator Filter Enable bit
 - 1 = Digital filter is enabled
 - 0 = Digital filter is disabled
- bit 2-0 **CFDIV<2:0>:** Comparator Filter Clock Divide Select bits
 - 111 = Clock Divide 1:128
 - 110 = Clock Divide 1:64
 - 101 = Clock Divide 1:32
 - 100 = Clock Divide 1:16
 - 011 = Clock Divide 1:8
 - 010 = Clock Divide 1:4
 - 001 = Clock Divide 1:2
 - 000 = Clock Divide 1:1

- Note 1:** See the Type C Timer Block Diagram (Figure 13-2).
Note 2: See the Type B Timer Block Diagram (Figure 13-1).
Note 3: See the High-Speed PWMx Module Register Interconnection Diagram (Figure 16-2).
Note 4: See the Oscillator System Diagram (Figure 9-1).

TABLE 30-8: DC CHARACTERISTICS: POWER-DOWN CURRENT (IPD)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended	
Parameter No.	Typ.	Max.	Units	Conditions
Power-Down Current (IPD)⁽¹⁾ – dsPIC33EP32GP50X, dsPIC33EP32MC20X/50X and PIC24EP32GP/MC20X				
DC60d	30	100	μA	-40°C
DC60a	35	100	μA	+25°C
DC60b	150	200	μA	+85°C
DC60c	250	500	μA	+125°C
Power-Down Current (IPD)⁽¹⁾ – dsPIC33EP64GP50X, dsPIC33EP64MC20X/50X and PIC24EP64GP/MC20X				
DC60d	25	100	μA	-40°C
DC60a	30	100	μA	+25°C
DC60b	150	350	μA	+85°C
DC60c	350	800	μA	+125°C
Power-Down Current (IPD)⁽¹⁾ – dsPIC33EP128GP50X, dsPIC33EP128MC20X/50X and PIC24EP128GP/MC20X				
DC60d	30	100	μA	-40°C
DC60a	35	100	μA	+25°C
DC60b	150	350	μA	+85°C
DC60c	550	1000	μA	+125°C
Power-Down Current (IPD)⁽¹⁾ – dsPIC33EP256GP50X, dsPIC33EP256MC20X/50X and PIC24EP256GP/MC20X				
DC60d	35	100	μA	-40°C
DC60a	40	100	μA	+25°C
DC60b	250	450	μA	+85°C
DC60c	1000	1200	μA	+125°C
Power-Down Current (IPD)⁽¹⁾ – dsPIC33EP512GP50X, dsPIC33EP512MC20X/50X and PIC24EP512GP/MC20X				
DC60d	40	100	μA	-40°C
DC60a	45	100	μA	+25°C
DC60b	350	800	μA	+85°C
DC60c	1100	1500	μA	+125°C

Note 1: IPD (Sleep) current is measured as follows:

- CPU core is off, oscillator is configured in EC mode and external clock is active; OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to Vss
- MCLR = VDD, WDT and FSCM are disabled
- All peripheral modules are disabled (PMDx bits are all set)
- The VREGS bit (RCON<8>) = 0 (i.e., core regulator is set to standby while the device is in Sleep mode)
- The VREGSF bit (RCON<11>) = 0 (i.e., Flash regulator is set to standby while the device is in Sleep mode)
- JTAG is disabled

**TABLE 30-38: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0)
TIMING REQUIREMENTS**

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	Symbol	Characteristic ⁽¹⁾	Min.	Typ. ⁽²⁾	Max.	Units	Conditions
SP70	FscP	Maximum SCK2 Input Frequency	—	—	Lesser of Fp or 11	MHz	(Note 3)
SP72	TscF	SCK2 Input Fall Time	—	—	—	ns	See Parameter DO32 (Note 4)
SP73	TscR	SCK2 Input Rise Time	—	—	—	ns	See Parameter DO31 (Note 4)
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO32 (Note 4)
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 (Note 4)
SP35	Tsch2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdoV2sch, TdoV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	
SP40	TdiV2sch, TdiV2scL	Setup Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP41	Tsch2diL, TscL2diL	Hold Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP50	TssL2sch, TssL2scL	$\overline{SS2} \downarrow$ to SCK2 \uparrow or SCK2 \downarrow Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS2} \uparrow$ to SDO2 Output High-Impedance	10	—	50	ns	(Note 4)
SP52	Tsch2ssH TscL2ssH	$\overline{SS2} \uparrow$ after SCK2 Edge	1.5 T _{CY} + 40	—	—	ns	(Note 4)
SP60	TssL2doV	SDO2 Data Output Valid after $\overline{SS2}$ Edge	—	—	50	ns	

- Note 1:** These parameters are characterized, but are not tested in manufacturing.
Note 2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.
Note 3: The minimum clock period for SCK2 is 91 ns. Therefore, the SCK2 clock generated by the master must not violate this specification.
Note 4: Assumes 50 pF load on all SPI2 pins.

TABLE 30-56: CTMU CURRENT SOURCE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions:3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
CTMU Current Source							
CTMUI1	IOUT1	Base Range ⁽¹⁾	0.29	—	0.77	μA	CTMUICON<9:8> = 01
CTMUI2	IOUT2	10x Range ⁽¹⁾	3.85	—	7.7	μA	CTMUICON<9:8> = 10
CTMUI3	IOUT3	100x Range ⁽¹⁾	38.5	—	77	μA	CTMUICON<9:8> = 11
CTMUI4	IOUT4	1000x Range ⁽¹⁾	385	—	770	μA	CTMUICON<9:8> = 00
CTMUFV1	VF	Temperature Diode Forward Voltage ^(1,2)	—	0.598	—	V	TA = +25°C, CTMUICON<9:8> = 01
			—	0.658	—	V	TA = +25°C, CTMUICON<9:8> = 10
			—	0.721	—	V	TA = +25°C, CTMUICON<9:8> = 11
CTMUFV2	VFVR	Temperature Diode Rate of Change ^(1,2,3)	—	-1.92	—	mV/°C	CTMUICON<9:8> = 01
			—	-1.74	—	mV/°C	CTMUICON<9:8> = 10
			—	-1.56	—	mV/°C	CTMUICON<9:8> = 11

Note 1: Nominal value at center point of current trim range (CTMUICON<15:10> = 000000).

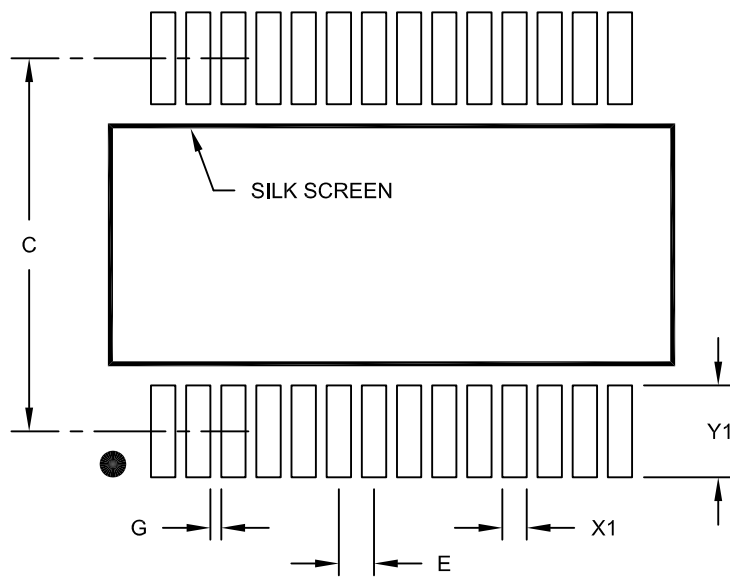
2: Parameters are characterized but not tested in manufacturing.

3: Measurements taken with the following conditions:

- VREF+ = AVDD = 3.3V
- ADC configured for 10-bit mode
- ADC module configured for conversion speed of 500 ksps
- All PMDx bits are cleared (PMDx = 0)
- Executing a while(1) statement
- Device operating from the FRC with no PLL

28-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	C	7.20		
Contact Pad Width (X28)	X1			0.45
Contact Pad Length (X28)	Y1			1.75
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2073A

Revision E (April 2012)

This revision includes typographical and formatting changes throughout the data sheet text.

All other major changes are referenced by their respective section in Table A-3.

TABLE A-4: MAJOR SECTION UPDATES

Section Name	Update Description
<p>“16-bit Microcontrollers and Digital Signal Controllers (up to 512-Kbyte Flash and 48-Kbyte SRAM) with High-Speed PWM, Op amps, and Advanced Analog”</p>	<p>The following 512-Kbyte devices were added to the General Purpose Families table (see Table 1):</p> <ul style="list-style-type: none"> • PIC24EP512GP202 • PIC24EP512GP204 • PIC24EP512GP206 • dsPIC33EP512GP502 • dsPIC33EP512GP504 • dsPIC33EP512GP506 <p>The following 512-Kbyte devices were added to the Motor Control Families table (see Table 2):</p> <ul style="list-style-type: none"> • PIC24EP512MC202 • PIC24EP512MC204 • PIC24EP512MC206 • dsPIC33EP512MC202 • dsPIC33EP512MC204 • dsPIC33EP512MC206 • dsPIC33EP512MC502 • dsPIC33EP512MC504 • dsPIC33EP512MC506 <p>Certain Pin Diagrams were updated to include the new 512-Kbyte devices.</p>
<p>Section 4.0 “Memory Organization”</p>	<p>Added a Program Memory Map for the new 512-Kbyte devices (see Figure 4-4). Added a Data Memory Map for the new dsPIC 512-Kbyte devices (see Figure 4-11). Added a Data Memory Map for the new PIC24 512-Kbyte devices (see Figure 4-16).</p>
<p>Section 7.0 “Interrupt Controller”</p>	<p>Updated the VECNUM bits in the INTTREG register (see Register 7-7).</p>
<p>Section 11.0 “I/O Ports”</p>	<p>Added tip 6 to Section 11.5 “I/O Helpful Tips”.</p>
<p>Section 27.0 “Special Features”</p>	<p>The following modifications were made to the Configuration Byte Register Map (see Table 27-1):</p> <ul style="list-style-type: none"> • Added the column Device Memory Size (Kbytes) • Removed Notes 1 through 4 • Added addresses for the new 512-Kbyte devices
<p>Section 30.0 “Electrical Characteristics”</p>	<p>Updated the Minimum value for Parameter DC10 (see Table 30-4). Added Power-Down Current (I_{pd}) parameters for the new 512-Kbyte devices (see Table 30-8). Updated the Minimum value for Parameter CM34 (see Table 30-53). Updated the Minimum and Maximum values and the Conditions for parameter SY12 (see Table 30-22).</p>